# **BGA Heat Sink - High Performance** maxiFLOW/superGRIP





Description: 29.00 x 29.00 x 7.50 mm BGA Heat Sink - High Performance maxiFLOW/superGRIP



Heat Sink Type: maxiFLOW
Heat Sink Attachment: superGRIP

Equivalent Part Number: N/A

\*Image above is for illustration purpose only.

### **Features & Benefits**

- Designed for 29 x 29 mm components
- · Requires minimal space around the component's perimeter; ideal for densely populated PCBs
- Allows the heat sink to be detached and reattached without damaging the component or the PCB, an important feature in the event a PCB may need to be reworked
- Strong, uniform attachment force helps achieve maximum performance from phase-changing TIMs
- Eliminates the need to drill mounting holes in the PCB

#### **Thermal Performance**

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	7.4 °C/W	5.9 °C/W	5 °C/W	4.5 °C/W	4.1 °C/W	3.8 °C/W	3.6 °C/W
	Ducted Flow	5.6	N/A	N/A	N/A	N/A	N/A	N/A

## **Product Detail**

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	ТІМ	Finish
	29.00 mm	29.00 mm	7.50 mm	42.4 mm	T766	BLUE-ANODIZED
*Image above is for illustration purpose only.	<ul> <li>Dimension</li> <li>Thermal papplication</li> <li>ATS reserperforman</li> <li>ATS certifities</li> </ul>	ves the right to upda	eight from the bottor provided for referent ate or change its proc	nce only. Actual performance only. Actual performance ducts without notice	ormance to improv	may vary by





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